



An Analysis Of Flash And HDD Technology Trends

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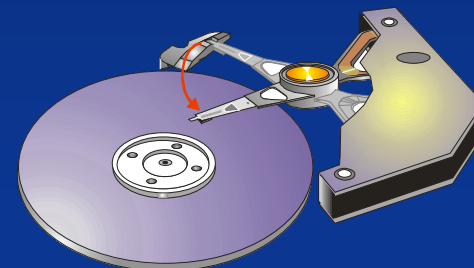
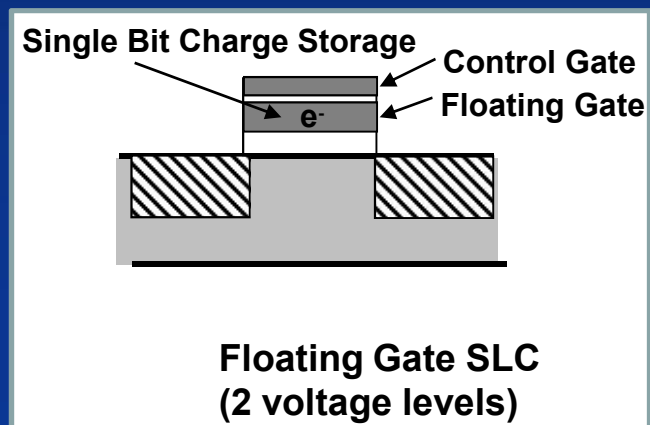
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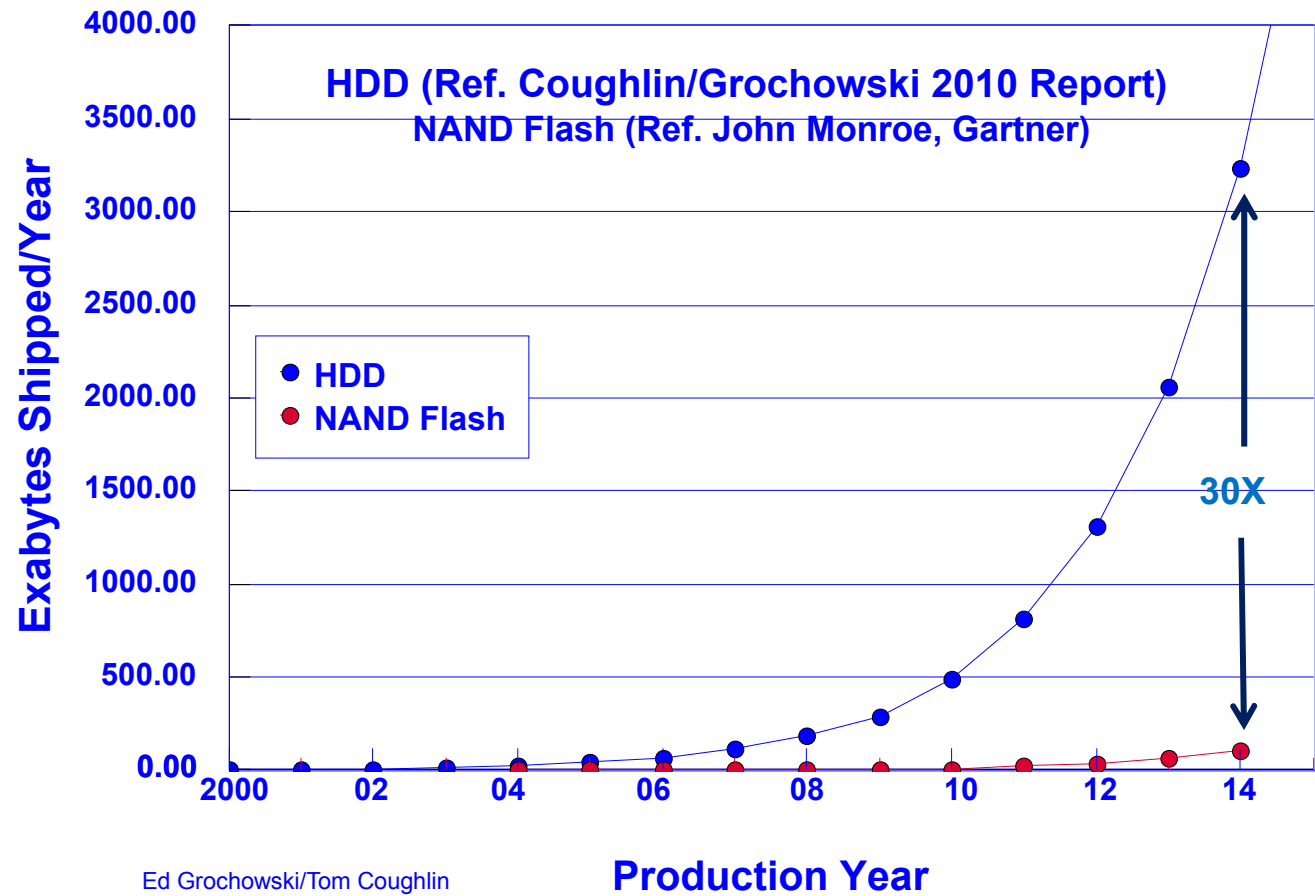
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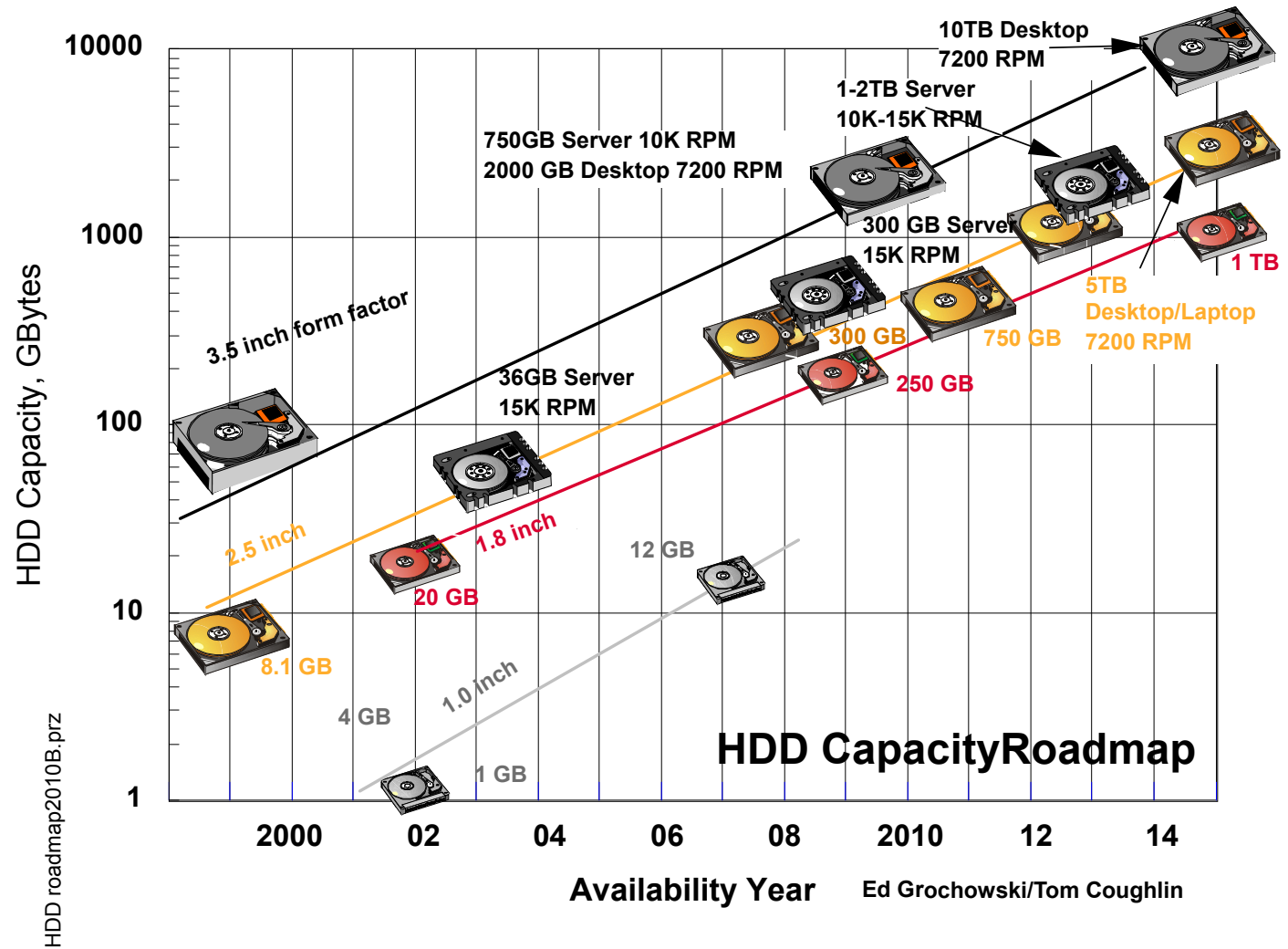


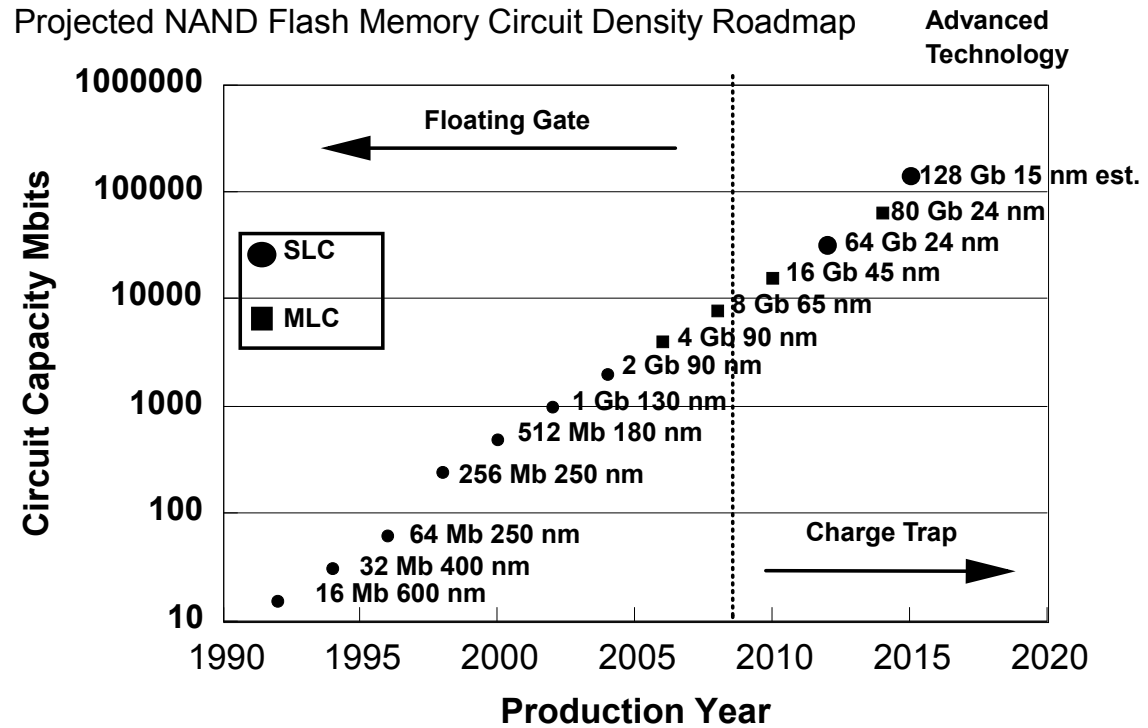


Introduction and Topics

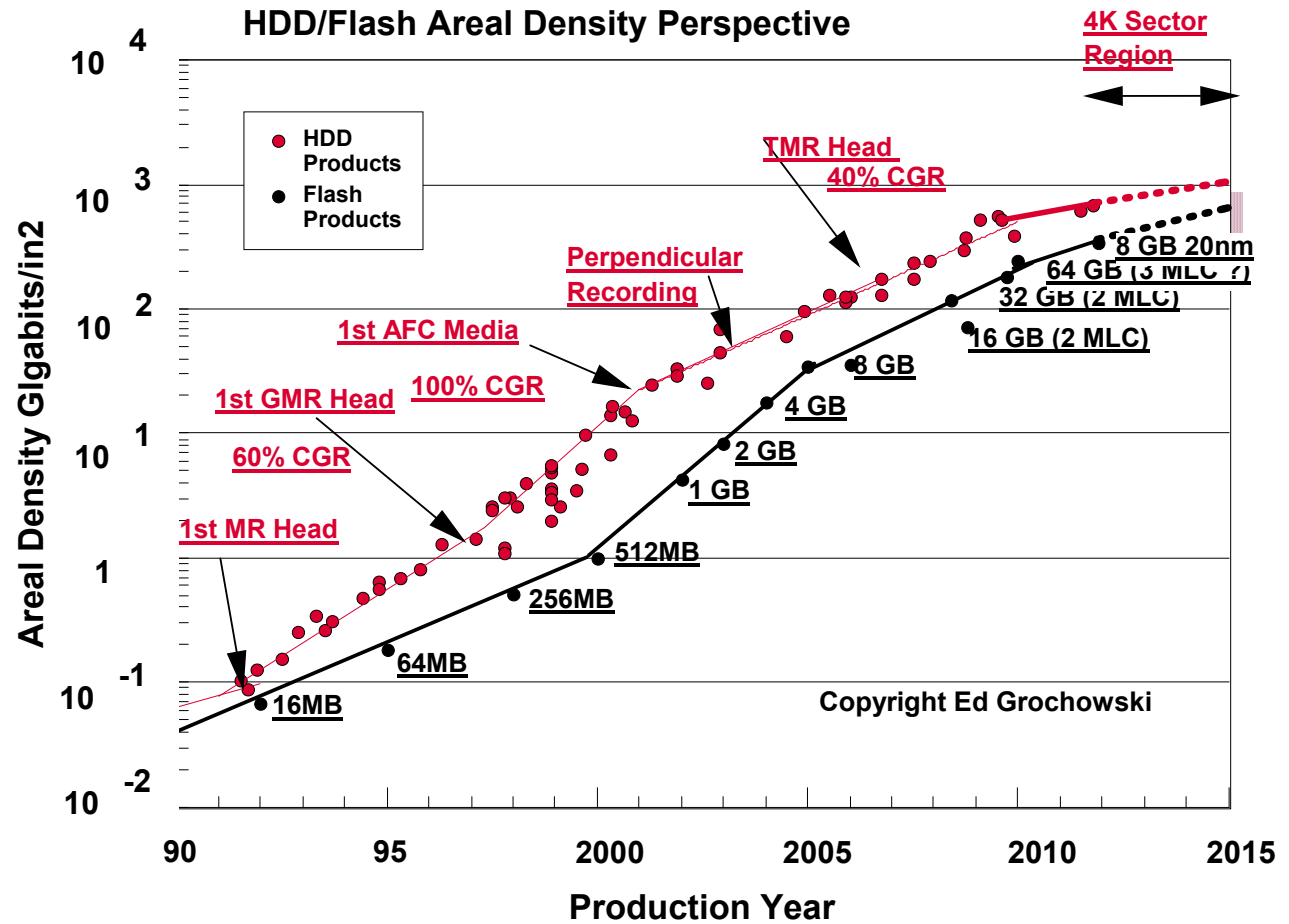
- 1. Analyze Storage Technology Trends For Flash and HDD**
- 2. Project To Where These Principal Storage Technologies Will Evolve**
- 3. Discuss Concerns With These Evolutions**
- 4. Project Data Densities**
- 5. Project Costs per Gbyte**
- 6. Analyze Lithography Challenges**
- 7. Future Designs for Flash/HDD**



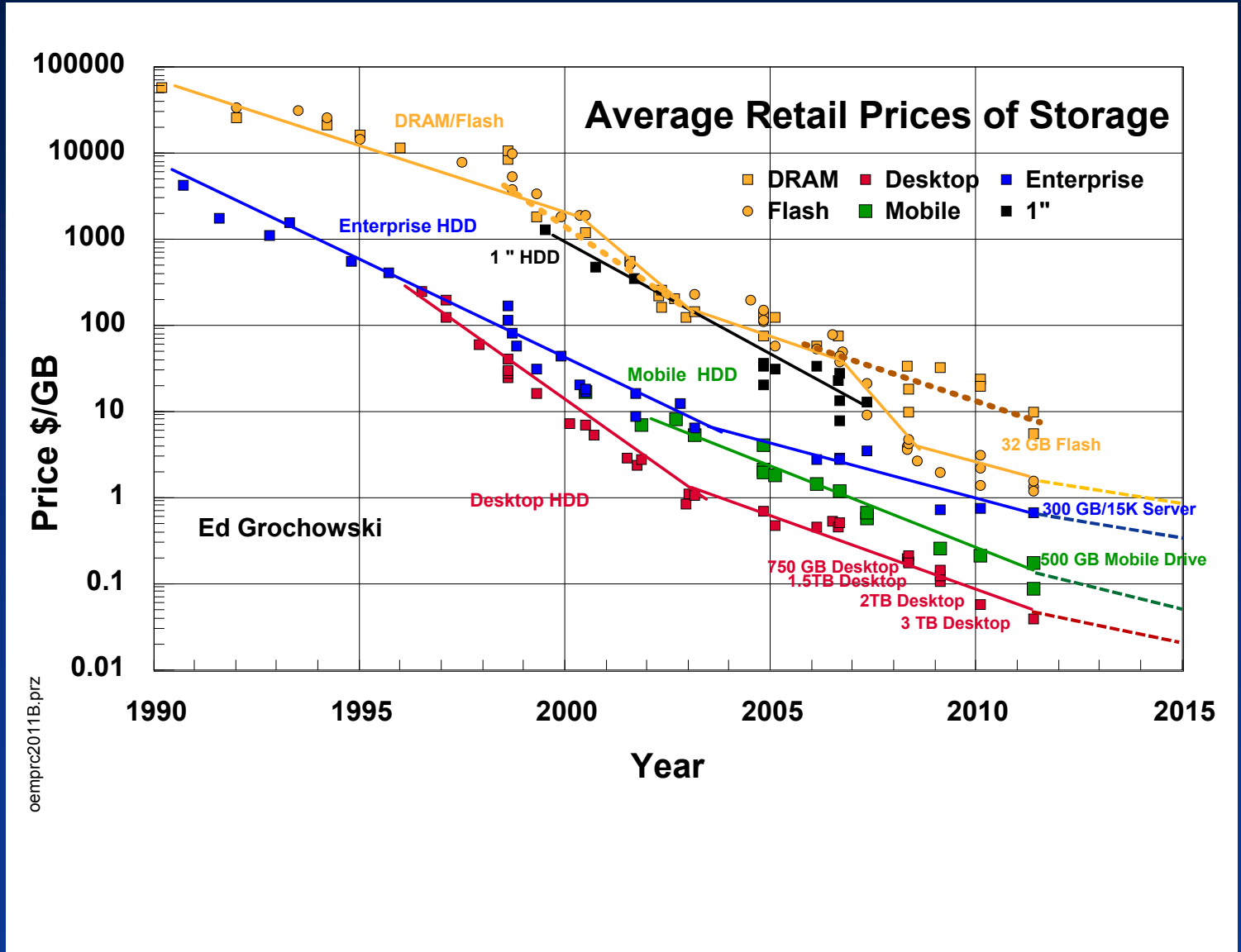




NAND Roadmap 2011X.prz



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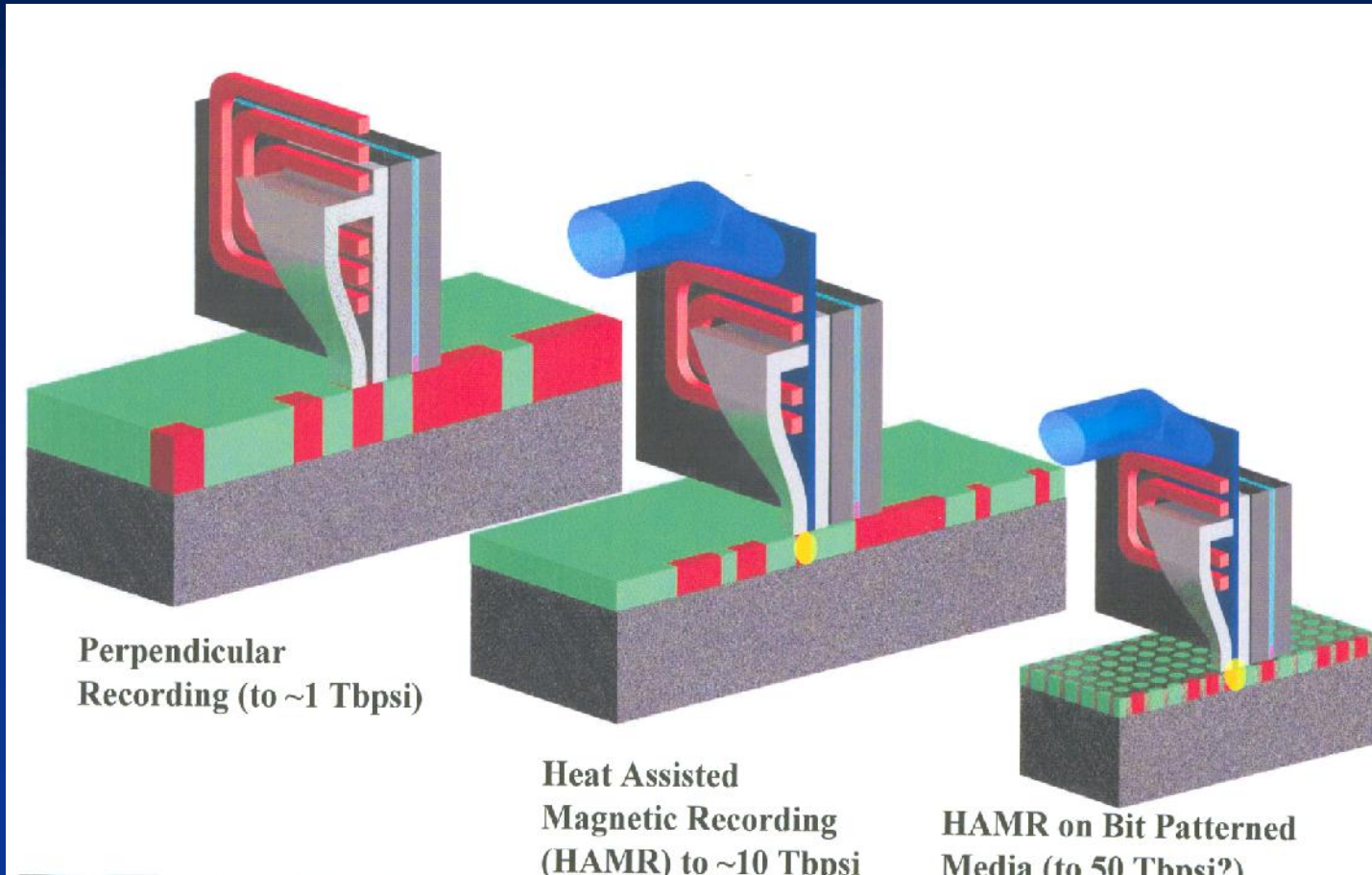




Magnetic Recording Cell

- The unique attribute of the magnetic bit cell in a hard disk drive (HDD) is that the bits are unpatterned → tremendous cost advantage
- The bit length is “sub lithographic”
- Bits are “magnetically” templated into the media using a single photo lithographically defined magnetic transducer
- Bit width is determined by the lithography used to form the write transducer. The smallest lithographically defined feature in the magnetic head is the read transducer $\sim \frac{1}{2}$ Track Pitch = **F**
- Bit length is determined without lithography! It is sub lithographic! It is defined by the distance the disk rotates during the time interval that alternating current pulses are applied to the write yoke.
- Bit length is limited by the resolution of the sensor, i.e. the read gap with dimensions **G** determined by depositions, not lithography
- An HDD Product Example (635 Gbit/in² Areal Density)
 - Minimum Lithography 37 nm = **F**
 - Bit Cell 74 nm x 13 nm
 - Smallest Bit Feature 13 nm → $\sim 33\%$ **F**, $\sim 50\%$ IC **F**

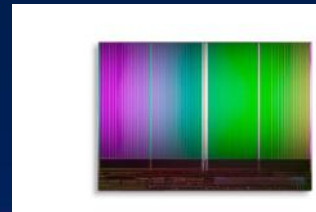
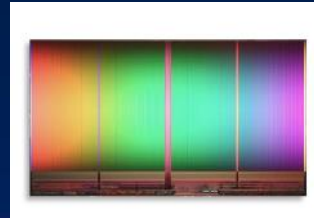
Three Major HDD Innovations



HDD Shingled Write

- 1. Is A Band Technology, Not A Sector Or Track (Marginally)**
- 2. Ideally Suited For Streaming Applications (>>Gbyte Movies)**
- 3. Many Potential Ideas For Writing Tracks**
- 4. Requirement For Correct Choices On Buffer Tracks And Band Sizes**
- 5. Involves Rewriting On Disk Or Buffer electronics Within Drive**
- 6. If Changes To OS Or System Electronics, Delays Are Probable, If Drop-in Technology, Applications Will Arrive Soon**

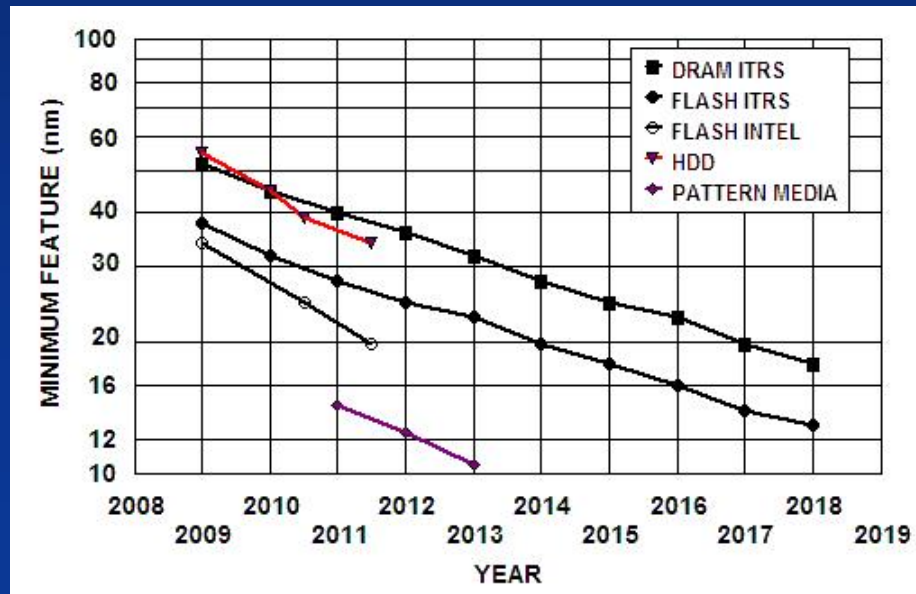
Cell Size Comparison



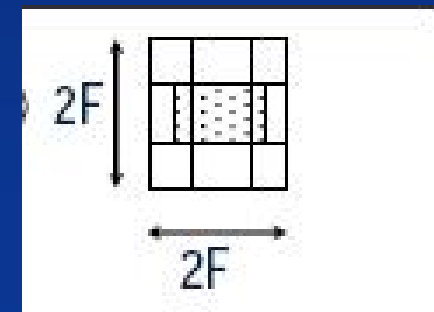
	8GB NAND Flash	8GB NAND Flash	375 GB 1 surface HDD
Surface Dimensions (Chip or Disk)	16.5 mm x 10.1 mm	12.5 mm x 9.5 mm	87.0 mm disk diameter 24.0 mm hub diameter 1.5 mm edge exclusions
Memory Surface Area	167 mm ²	118 mm ²	5491 mm ²
Active Memory Area	~ 122 mm ² (73%)	~ 71 mm ² (65%)	~ 4969 mm ² (90%)
Minimum Lithography	F = 25 nm	F = 20 nm	F = 37 nm
Active Bit Cell Area	1906 nm ² = 3.0 F ²	1109 nm ² = 2.8 F ²	981 nm ² = 0.7 F ²
Bit Cell Dimension	44 nm x 44 nm	33 nm x 33 nm	74 nm x 13 nm
Maximum Areal Density	330 Gb/in ²	560 Gb/in ²	635 Gb/in ²

Lithography and NAND Flash

- Typical NAND cells formed with sub 30 nm lithography with Intel-Micron providing leading edge devices at 25 nm to 20 nm
- Bit cell area approaches $2.5 F^2$ (F is the minimum lithographic feature) for Self Aligned STI multi level (2 bit per cell) designs
- HDD cells formed with minimum features close to DRAM requirements
- Patterned Media cells will require substantial “invention” in lithography to meet density goals

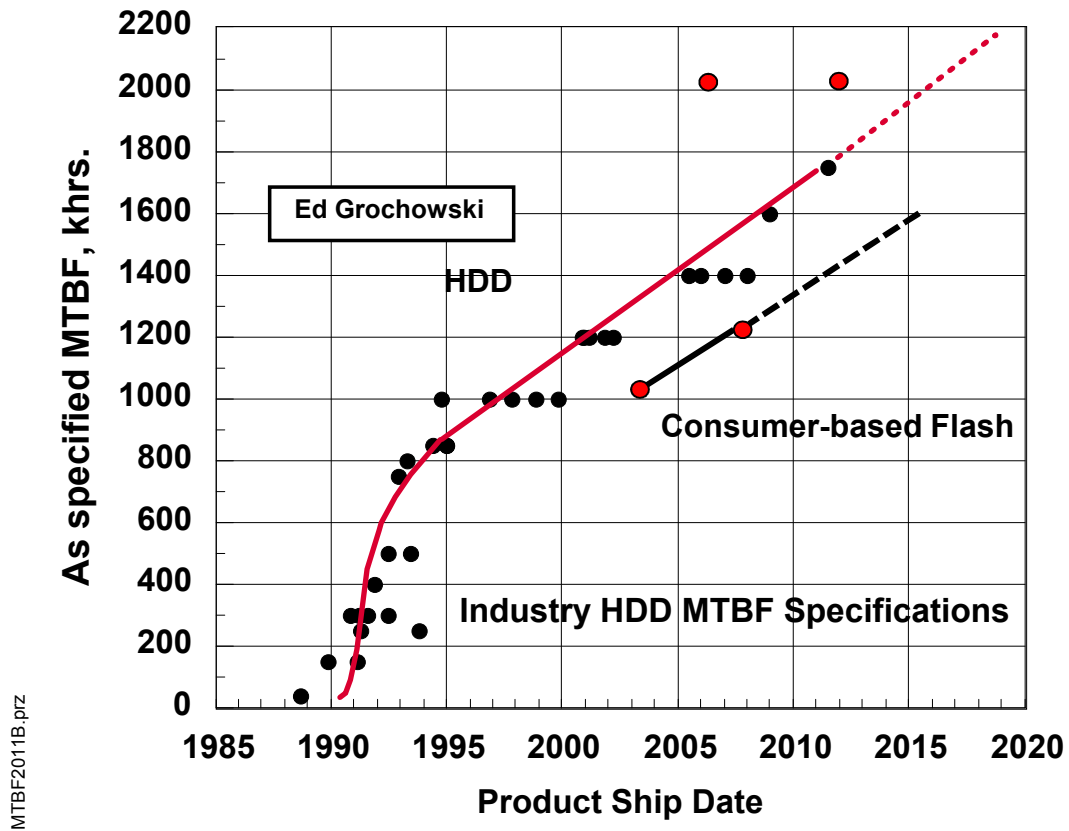


Multi Level NAND Cell

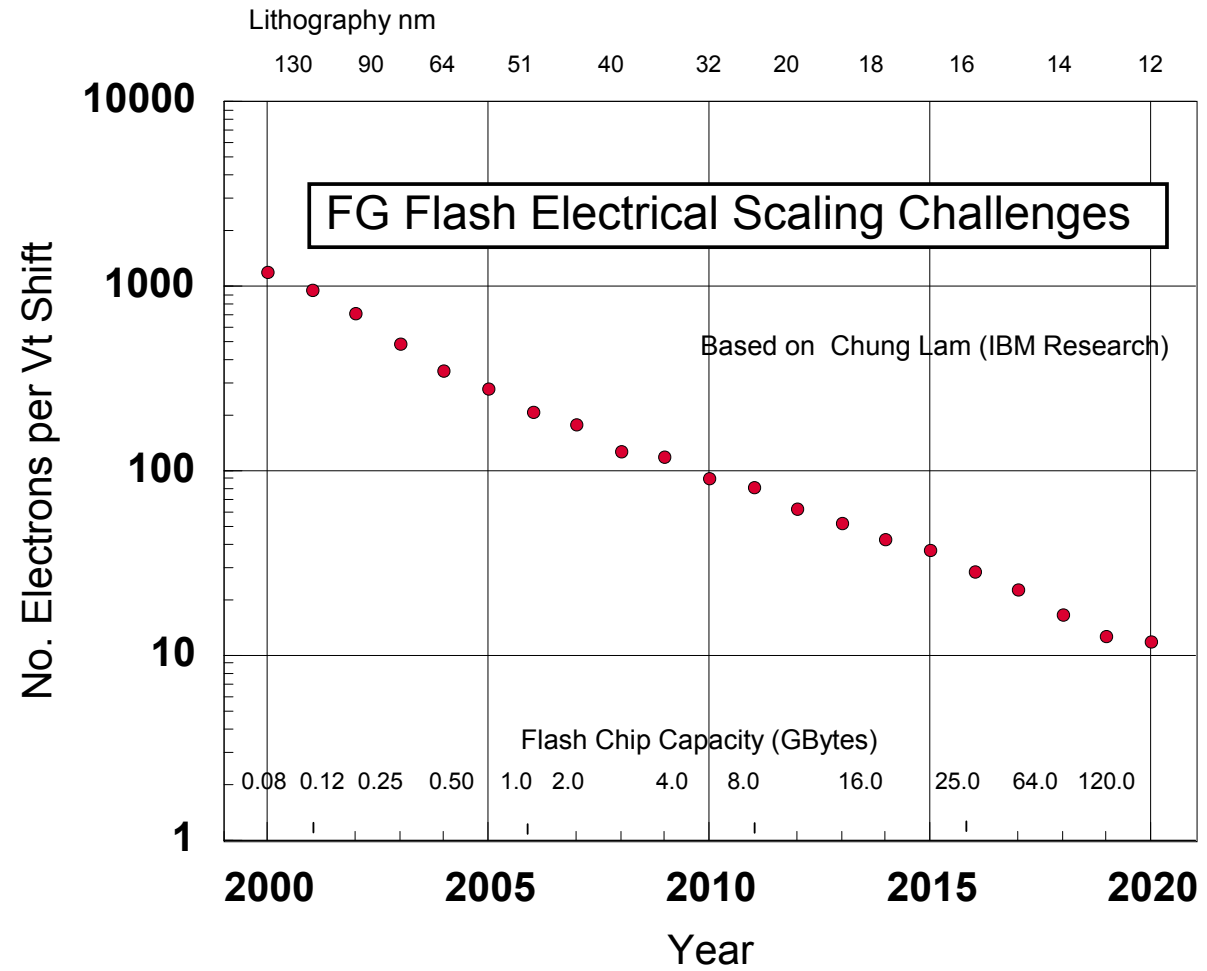


MTBF Specifications

Enterprise-based Flash

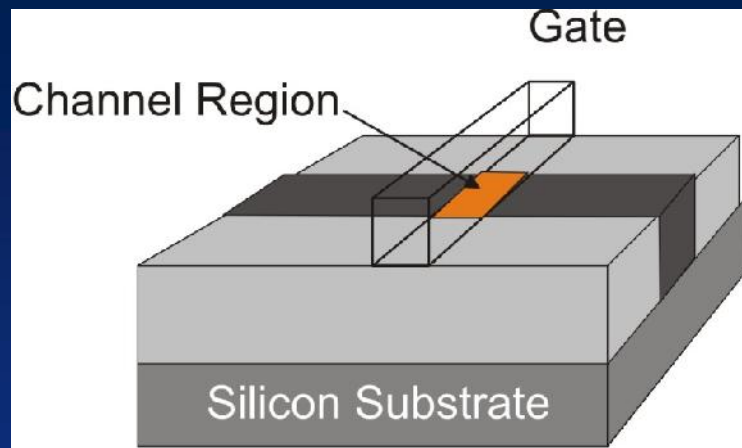


Flash Scaling

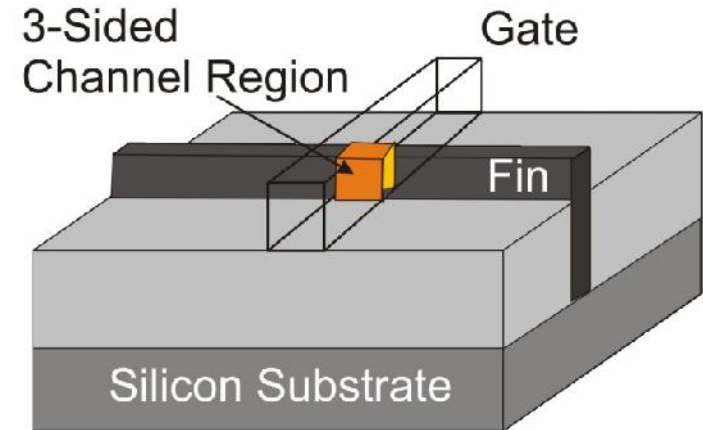


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New Transistor Designs



Standard Transistor



3D Transistor (INTEL)

1. Better Current Control
2. Reduces Current Leakage
3. Allows Closer Packing



Flash Scaling Challenges

- 1. >15 nm Lithography (EUV Technology Too Expensive For Flash, Also HDD)**
- 2. Fewer Electrons \gg 100 (Leakage >1 Electron Per Month)**
- 3. Electric Field Stress During Programming Too High**
- 4. Write Endurance Degrades**



Conclusion

- 1. Expect Significantly Reduced Scaling And Capacity Progress- Flash And HDD-In Future**
- 2. New Processing And Structural Techniques Limited By Implementation Costs**
- 3. Storage Requirements Will Continue Vigorous Demands For Both Flash And HDD Products**
- 4. Door Is Open For Alternative Technologies (FeRam, MRAM Are Imbedded Technologies; PCM Is Crosspoint)**